

TO :

文件编号

HXA-L52-10(01)

发行日期

2019年12月15日

## 承认规格书

种类：SMD Power Choke Coil系列号：HXPC1206H-Series客户料号：                                

### 客户承认栏

客户承认栏	
承认日期	年      月      日

(贵司承认后请签署一份返回华信安电子, 谢谢!)

### 厦门华信安电子科技有限公司技术质量部

承 认	确 认	作 成
龙梅	梁峰	王亮

TEL : 0592-6301603      FAX : 0592-5205265

Http : [www.xmisnd.com](http://www.xmisnd.com)

<b>SMD Power Choke Coil</b>	<b>HXPC1206H-Series</b>
-----------------------------	-------------------------

<b>ECN HISTORY LIST</b>					
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	19/12/15	新發行	龙梅	梁峰	王亮
備					
注					

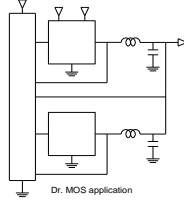
### 1. Features

1. Alloy Sponge Powder inductor.
2. Compact design.
3. High current , low DCR , high efficiency.
4. Very low acoustic noise and very low leakage flux noise.
5. High reliability.
6. 100% Lead(Pb)-Free and RoHS compliant.

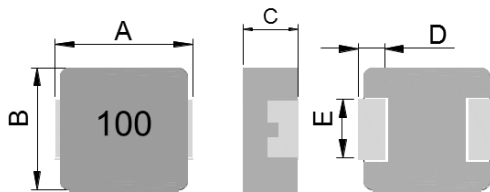


### 2. Applications

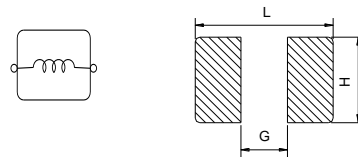
Note PC power system , incl. IMVP-6  
DC/DC converter .



### 3. Dimensions



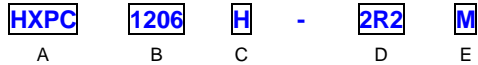
#### Recommend PC Board Pattern



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
HXPC1206H	13.45±0.35	12.8±0.5	6.0Max	2.0±0.5	5.0±0.3

L(mm)	G(mm)	H(mm)
14.2	8.0	5.0

### 4. Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Inductance
- E: Inductance Tolerance
- AxC
- Magnetic metal powder
- 2R2=2.2uH
- M=±20%

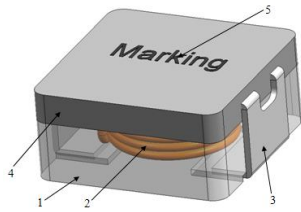
## 5. Specification

Part Number	Inductance L0 ( $\mu$ H) $\pm$ 20% @ 0 A	I sat (A) Typ.	I rms (A) Typ	DCR (m $\Omega$ ) Max. @25°C
HXPC1206H-4R7M	4.70	24.0	15.0	9.0
HXPC1206H-5R6M	5.60	22.5	13.0	11.0
HXPC1206H-6R8M	6.80	19.0	12.0	13.5
HXPC1206H-8R2M	8.20	13.5	11.0	16.0
HXPC1206H-100M	10.0	12.5	10.0	20.7
HXPC1206H-120M	12.0	10	9.0	23.0
HXPC1206H-150M	15.0	9.0	8.5	29.0
HXPC1206H-180M	18.0	8.0	7.5	35.0
HXPC1206H-220M	22.0	7.5	7.0	39.5
HXPC1206H-270M	27.0	6.5	6.0	56.0
HXPC1206H-330M	33.0	6.0	5.5	75.0
HXPC1206H-470M	47.0	5.5	5.0	90.0
HXPC1206H-680M	68.0	4.5	4.0	140.0
HXPC1206H-101M	100	3.5	3.0	200.0
HXPC1206H-121M	120	3.2	2.0	235.0
HXPC1206H-151M	150	2.7	1.5	350.0

Note:

1. Test frequency : L : 100KHz /1.0V;
2. All test data referenced to 25°C ambient.
3. Testing Instrument : L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately  $\Delta$  t of 40°C (keep 1min.).
5. Saturation Current (I sat) will cause L0 to drop 20% typical. (keep quickly).
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

## 6. Material List



NO	Items	Materials
1	Core	Alloy Sponge Powder .
2	Wire	Polyurethane copper wire
3	Solder Plating	100% Pb free solder
4	MARKING	Ink(black)

## 7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-55~+125°C	
Storage temperature and Humidity range	1. -10~+40°C, 50~60%RH (Product with taping) 2. -40~+125°C (on board)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	△ L20% typical.	Saturation DC Current (Isat) will cause L0 to drop △ L(%)(keep quickly).
Heat Rated Current (Irms)	Approximately △ T ≤ 40°C	Heat Rated Current (Irms) will cause the coil temperature rise △ T(°C) without core loss. 1. Applied the allowed DC current(keep 1 min.). 2. Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
High Temperature Exposure Test	Electric specifications should be satisfied	Temperature: 125±2°C. Duration: 1000±12hrs. Measured at room temperature after placing for 2 to 3hrs. (MIL-PRF-27)
Biased Humidity Test		Humidity: 85±3%RH. Temperature: 85±2°C. Duration: 1000±12hrs. Measured at room temperature after placing for 2 to 3hrs (AEC-Q200-REV C)
Thermal shock test		Condition for 1 cycle Step1: -40+0 / -2°C 15±1 min. Step2: Room temperature within ≤ 0.2 min. Step3: +125+2 / -0°C 15±1min. Number of cycles: 300 Measured at room temperature after placing for 2 to 3 hrs. (AEC-Q200-REV C)
Vibration test		Frequency: 10-2000-10Hz for 20 min. Amplitude: Parts mounted within 2" from any secure point. Directions and times: X, Y, Z directions for 20 min. This cycle shall be performed 12 times in each of three mutually perpendicular directions (Total 12hours). (MIL-STD-202 Method 204 D Test condition B)
Reflow test		Pre-heat : 150±5°C Duration : 5 minutes Temperature : 260±5°C , 20~40 seconds (IPC/JEDEC J-STD-020C)
Solder test		Terminals should be covered by over 95% solder on visual inspection

## 8. Soldering and Mounting

### (1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### (2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

### (3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4-5sec.

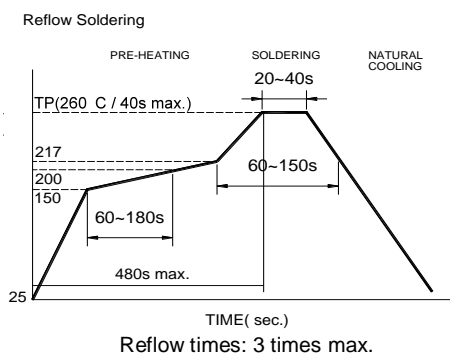


Fig.1

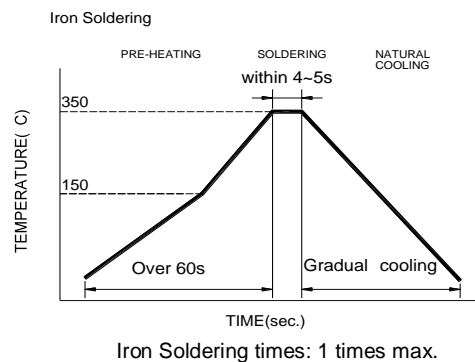
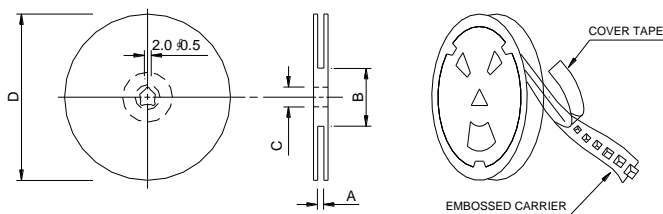


Fig.2

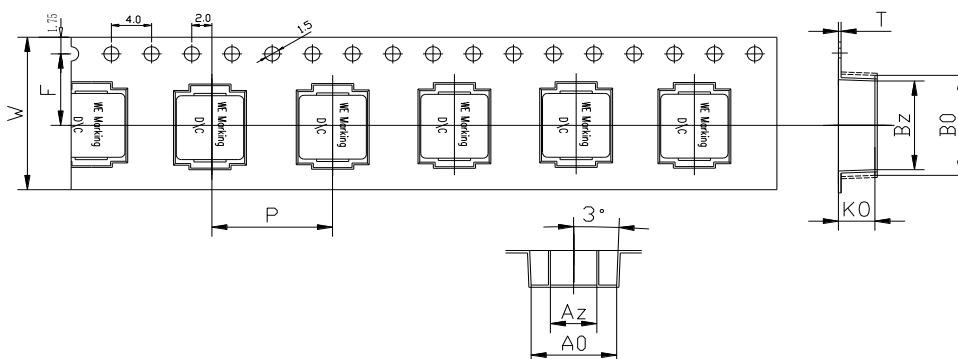
### 9. Packaging Information

#### (1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.4+2/-0	100±2	13.5±0.5	330

#### (2) Tape Dimension

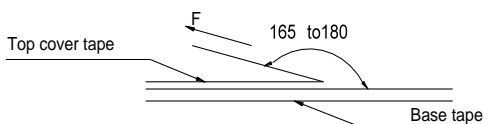


Series	Size	Bo(mm)	Bz(mm)	Ao(mm)	Az(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)
HXPC	1206	14.2±0.1	13.0±0.1	13.0±0.1	7.0±0.1	7.0±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05

#### (3) Packaging Quantity

<b>HXPC</b>	<b>1206</b>
Chip / Reel	500

#### (4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

#### Application Notice

- Storage Conditions (component level)
  - To maintain the solderability of terminal electrodes:
    - ISND products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
    - Temperature and humidity conditions: Less than 40°C and 60% RH.
    - Recommended products should be used within 12 months form the time of delivery.
    - The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  - Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  - The use of tweezers or vacuum pick up is strongly recommended for individual components.
  - Bulk handling should ensure that abrasion and mechanical shock are minimized.

单击下面可查看定价，库存，交付和生命周期等信息

[>>ISND\(华信安\)](#)